Title (en)
ELECTRONIC MODULE, AND METHOD FOR PRODUCING ONE

Title (de)
ELEKTRONIKMODUL SOWIE VERFAHREN ZUR HERSTELLUNG EINES SOLCHEN

Title (fr)
MODULE ÉLECTRONIQUE ET SON PROCÉDÉ DE FABRICATION

Publication
EP 1969626 A1 20080917 (DE)

Application
EP 06819359 A 20061109

Priority
• EP 2006068282 W 20061109
• DE 102005062783 A 20051228

Abstract (en)
[origin: DE102005062783A1] The module has an electrically conductive lower substrate (16) with a base body (54), and an upper substrate (18) fastened to the lower substrate. A power component (22) is arranged on the lower substrate, and the upper substrate is equipped with electronic component (40) e.g. microprocessor. The upper substrate has a smaller base surface (19) than the body of the lower substrate, where the power component is fastened to the lower substrate at the outer side of an outer periphery of the upper substrate. The body and the upper substrate are coated together with a plastic body (62). An independent claim is also included for a method for manufacturing an electronic module.

IPC 8 full level
H01L 23/495 (2006.01); **H01L 25/07** (2006.01)

CPC (source: EP US)
H01L 25/162 (2013.01 - EP US); **H05K 1/021** (2013.01 - EP US); H01L 23/49531 (2013.01 - EP US); H01L 23/49833 (2013.01 - EP US); H01L 23/49861 (2013.01 - EP US); H01L 2224/48091 (2013.01 - EP US); H01L 2224/48227 (2013.01 - EP US); H01L 2924/13055 (2013.01 - EP US); H01L 2924/13091 (2013.01 - EP US); H01L 2924/19105 (2013.01 - EP US); H01L 2924/3025 (2013.01 - EP US); H05K 1/0306 (2013.01 - EP US); H05K 1/182 (2013.01 - EP US); H05K 3/0061 (2013.01 - EP US); H05K 2201/10446 (2013.01 - EP US); H05K 2203/049 (2013.01 - EP US)

Citation (search report)
See references of WO 2007079997A1

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)
DE 102005062783 A1 20070705; CN 101351882 A 20090121; CN 101351882 B 20101229; EP 1969626 A1 20080917; JP 2009522758 A 20090611; JP 4886791 B2 20120229; US 2008247142 A1 20081009; US 8169791 B2 20120501; WO 2007079997 A1 20070719

DOCDB simple family (application)
DE 102005062783 A 20051228; CN 200680049576 A 20061109; EP 06819359 A 20061109; EP 2006068282 W 20061109; JP 2008547912 A 20061109; US 9292006 A 20061109